PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6546972

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JING-EN LUAN	06/10/2019

RECEIVING PARTY DATA

Name:	STMICROELECTRONICS PTE LTD
Street Address:	28 ANG MO KIO INDUSTRIAL PARK 2
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	569508

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16874392

CORRESPONDENCE DATA

Fax Number: (206)682-6031

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2066224900
Email: kristinan@seedip.com
Correspondent Name: ZACHARY SAKOI, SEED IP LAW GROUP LLP
Address Line 1: 701 5TH AVE
Address Line 2: SUITE 5400
Address Line 4: SEATTLE, WASHINGTON 98104

ATTORNEY DOCKET NUMBER:	18-TPY0507US02/817063.459
NAME OF SUBMITTER:	ZACHARY M. SAKOI
SIGNATURE:	/Zachary M. Sakoi/
DATE SIGNED:	02/11/2021

Total Attachments: 2
source=817063.459#page1.tif
source=817063.459#page2.tif

This assignment is intended for USAN 16/874,392, filed May 14, 2020, which claims priority to 62/861,923, filed June 14, 2019.

ASSIGNMENT

Application Number: 62/861,923
Filing Date: June 14, 2019
Application Country/Region: *United States of America*
Application Title: ***WAFER LEVEL CHIP SCALE PACKAGE HAVING VARYING THICKNESSES***

Assignee: ***STMICROELECTRONICS PTE LTD***
Assignee being a company, corporation, or juristic entity of: ***Singapore, Singapore***
Assignee's principal place of business: ***28 Ang Mo Kio Industrial Park 2, Singapore, Singapore, 569508***

I, the below identified and undersigned inventor or co-inventor, as the case may be, of residence listed below, for and in consideration of good and valuable consideration, the receipt, sufficiency, and adequacy of which are hereby acknowledged, hereby transfer and assign to Assignee, its legal representatives, successors, and assigns, my entire right, title, and interest in and to the inventions for which the above identified patent application is made and describes (hereinafter referred to as "the Patent Rights"), together with any and all patents or patent applications anywhere worldwide to which any of the Patent Rights directly or indirectly claims priority, including but not limited to provisional applications thereof, or for which any of the Patent Rights directly or indirectly forms a basis for priority, together with all existing and/or future continuations, continuations-in-part, continuing prosecution applications, requests for continuing examinations, divisions, reissues, reexaminations, extensions, registrations, and foreign counterparts of any item in any of the foregoing, together with the right to sue for and be entitled to any damages, injunctive relief, and any other remedies of any kind for past, current, and future infringement thereof, together with all rights worldwide in the Patent Rights; said entire right, title, and interest, to be held and enjoyed by the Assignee for its own use and enjoyment and for the use and enjoyment of their legal representatives, successors, and assigns to the full end of the term for which the aforementioned rights may be granted anywhere in the world.

I hereby further agree to assist in and execute all documents needed now or in the future to perfect, obtain, and secure the aforementioned rights to Assignee, its legal representatives, successors, and assigns, for any jurisdiction in the world. At the expense of Assignee, or its legal representatives, successors, or assigns, I agree to assist in any legal proceedings, sign all lawful papers, make all lawful oaths, and generally do everything possible to aid Assignee, its legal representatives, successors, and assigns, to enforce the aforementioned rights in any and all countries and regions worldwide.

I hereby grant Assignee, along with the following Assignee representatives, the power to insert in this Assignment any further identification that may be necessary or desirable in order to comply with the rules for recordation of this document any place in the world: All practitioners at Customer Number 30423.

ST Docket Number: ***18-TPY-0507US01***

If there are co-inventors listed below, the signatures of all the inventors need not appear on the same page, and each inventor may sign this Assignment in multiple counterparts, such that each separately signed counterpart of this Assignment constitutes an original Assignment for the inventor(s) that signed such counterpart.

Inventor Name	**Residence (City, State, Country)**	**Inventor Signature**	**Date Signed**
Jing-En LUAN	*BLK 35 #08-333 Lorong 5 Toa Payoh, Singapore, Singapore 310035*		10/06/2019

Seed Ref. No. 817063.459P1 | 6787774_1